### Welcome to O-leading

O-Leading strives to be your one stop solution partner in EMS supply chain, including PCB design , PCB fabrication and PCB assembly (PCBA). We provide some of the most advanced PCB technology, including HDI PCBs, multilayer PCBs, Rigid-Flexible PCBs. We can support from quick turn prototype to medium & mass Production. Printed circuit board supplier

In general, our global customers are very impressed with our services:rapid response, competitive price and quality commitment.Providing more valuable technical service and overall solution is the way O-leading forward.

Looking to the future, O-leading will concentrate on the innovation and development of electronics manufacturing technology as always, and make persistent efforts on PCB & PCBA one-stop service to provide first-class services and create more value for our customers.

We are professional PCB manufacturer with ten years experiences . Products range-single, double side ,multi-layer PCB ,flexible PCB and MCPCB.

We can provide fast prototype service – S/S in 24hrs , 4-8layers in 48-96 working hrs production time. oem mobile phones pcb circuit board with power supply

Copper plate holes minmum 0.025 avg, 0.020 min. Holes need to be plugged. Pack with colorless transparent bubble film ,25PCS/ bag, put desiccant in flank, put humidity indicator card on top side.

#### Multilayer pcb manufacturer china

Place of Origin:	Guang dong, China (Mainland)	Brand Name:	O-Leading
Base Material:	FR-4,,Aluminum	Copper Thickness:	0.5oz-5oz
Min. Hole Size:	0.2mm	Min. Line Width:	0.2mm
Surface Finishing:	immersion gold ,OSP,lead free HASL	Board Thickness	0.1-5mm
applicable to:	led,mobile phone,air conditioners,washing machines	character:	Industrial Control pcb
certificates:	ISO9001,UL,RoHS,SGS	Q/CTN:	10PCS-100PCS
weight:	0.01kg -5kg	MOQ:	10pcs
color	blue ,red ,green,black.yellow	Min. Line Spacing	0.2mm
Model Number	power bank pcb assembly pcba manufacturer	price	\$0.1-\$10
desigh type	client requirement	size	0.01m3-10m3

multilayer PCB manufacturer in china

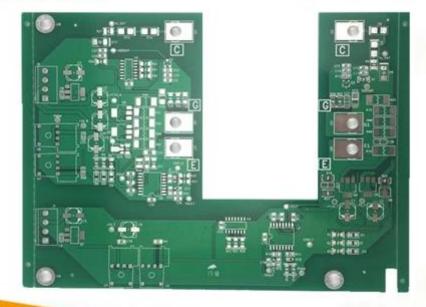












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#### Factory PCB



Automatic vacuum press machine



Drilling Machine



Pattern Plating Machine



Scrubbing Machine



Developing Machine



Routing Machine



High-speed flying probe machine



E-test Machine

#### Factory SMT













## Certifications







Test Report

Test Report No. SZXEC1900530401 Date: 30 Mar 2019 Page 2 of 6

Test Results

Test Part Description :

Specimen No. SGS Sample ID Description
SN1 SZX19-005304.001 Green\*PCB\*\*

(1) 1 mg/kg = 1 ppm = 0.0001% (2) MDL = Method Detection Limit

(3) ND = Not Detected ( < MDL )

(4) "-" = Not Regulated

RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU

Test Method : With reference to IEC 62321-4:2013+A1:2017, IEC62321-5:2013, IEC62321-7-2:2017, IEC 62321-6:2015 and IEC62321-8:2017, analyzed by ICP-OES, UV-Vis and GC-MS.

Test Item(s)	Limit	Unit	MDL	001
Cadmium (Cd)	100	mg/kg	2	ND
Lead (Pb)	1,000	mg/kg	2	8
Mercury (Hg)	1,000	mg/kg	2	ND
Hexavalent Chromium (Cr(VI))	1,000	mg/kg	8	ND
Sum of PBBs	1.000	mg/kg		ND
Monobromobiphenyl		mg/kg	5	ND
Dibromob iphen yl	12	mg/kg	5	ND
Tribromobiphenyl	15	mg/kg	5	ND
Tetrabromobiphenyl		mg/kg	5	ND
Pentabromobiphenyl		mg/kg	5	ND
Hexabromobiphenyl		mg/kg	5	ND
Heptabromobiphenyl		mg/kg	5	ND
Octabromobiphenyl		mg/kg	5	ND
Nonabromobiphenyl	6	mg/kg	5	ND
Decabromobiphenyl		mg/kg	5	ND
Sum of PBDEs	1,000	mg/kg		ND
Monobromodiphenyl ether		mg/kg	5	ND
Dibromodiphenyl ether	12	mg/kg	5	ND
Tribromodiphenyl ether	2	mg/kg	5	ND
Tetrabromodiphenyl ether	-	mg/kg	5	ND
Pentabromodiphenyl ether		mg/kg	5	ND



The following sample(s) was/were submitted and identified on behalf of the clients as : OSP

SGS Job No.: RP19-005089 - SZ Date of Sample Received : 22 Mar 2019

O-LEADING SUPPLY CHAIN (HK) CO., LIMITED

22 Mar 2019 - 30 Mar 2019 Testing Period :

Test Requested : Selected test(s) as requested by client. Test Results :

Conclusion:

Please refer to next page(s).

1313,FLOOR 13, FORTUNE BUILDING, DANSHUI TOWN, HUIYANG DISTRICT, HUIZHOU, GUANGDONG,

Based on the performed tests on submitted sample(s), the results of Lead. Mercury, Cadmium, Hexavalent chiromium, Polybrominated biphenyls (PBBs), Polybrominated diphenyl ethers (PBBcs) and Phthalates such as Bis(2-ethylbexyl) phthalate (DBFP). Bibutyl phthalate (DBFP). Tolbutyl phthalate (DBFP), and Diisobutyl phthalate (DBFP) comply with the limits as set by RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/85/EU.

Signed for and on behalf of SGS-CSTC Standards Technical Services Co., Ltd. Shenzhen Branch

lina





# Packaging & Delivery

# Shipping service











Quick Turn Lead Time				
Layer Count:	Lead Tim	Special Requirement		
1L/2L	2-3days	24 Hours,48 Hours		
4L	3-4days	48 Hours		
6L	4-5days	72 Hours		
8L	5-6days	NA		
10L	6-7days	NA		
12L	7-8days	NA		
14L	8-9days	NA		

	Standard Lead Time				
Layer Count:	Sample Lead Time	Volume order lead time			
2L	4 days	10 days			
4L	5 days	11 days			
6L	6 days	12 days			
8L	8 days	14 days			
10L	10 days	16 days			
12L	12 days	18 days			
14L	14 days	20 days			
16-32L	18 days	24 days			

## **Process Capability**

### **PCB Production Capabilities**

Layer Count: 1Layer-32Layer

Finished copper thickness ☐ 1/3oz-12oz

Min Line width/spacing internal ☐ 3.0mil/3.0mil Min Line width/spacing external: 4.0mil/4.0mil

Max Aspect Ratio: 10:1

Board thickness[] 0.2mm-5.0mm
Max Panel size(inches): 635\*1500mm
Minimum Drilled Hole Size: 4mil
Plated Hole Tolerance: +/-3mil
Blind/Buried Vias (All Types): YES
Via Fill(Conductive,Non-Conductive): YES

Base Material: FR-4,FR-4high Tg.Halogen free material,Rogers,Aluminium base,Polyimide,

**Heavy Copper** 

Surface finishes: HASL,OSP,ENIG,HAL-LF,Immersion silver,Immersion Tin,Gold fingers,Carbon ink

### **SMT Production Capabilities**

PCB Material: FR-4,CEM-1,CEM-3,Aluminum-based board

Max PCB size: 510x460mm Min PCB size∏50x50mm PCB Thickness∏0.5mm-4.5mm

PCB Thickness 0.5mm-4.5m Board thickness 0.5-4mm Min Components size: 0201

Standard chip size component: 0603 and larger

Component max height

☐15mm

Min lead pitch: 0.3mm Min BGA ball pitch:0.4mm

Placement precision: +/-0.03mm